

SOT1444-12

WLCSP49, wafer level chip-scale package, 49 terminals, 0.4 mm pitch, 2.915 mm x 3.142 mm x 0.564 mm body

28 May 2018

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP49
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	20-4-2018
Manufacturer package code	98ASA00718D

Table 1. Package summary

Parameter		Min	Nom	Max	Unit
package length		-	3.142	-	mm
package width		-	2.915	-	mm
seated height		-	0.564	-	mm
nominal pitch		-	0.4	-	mm
actual quantity of termination		-	49	-	A/A



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2. Package outline

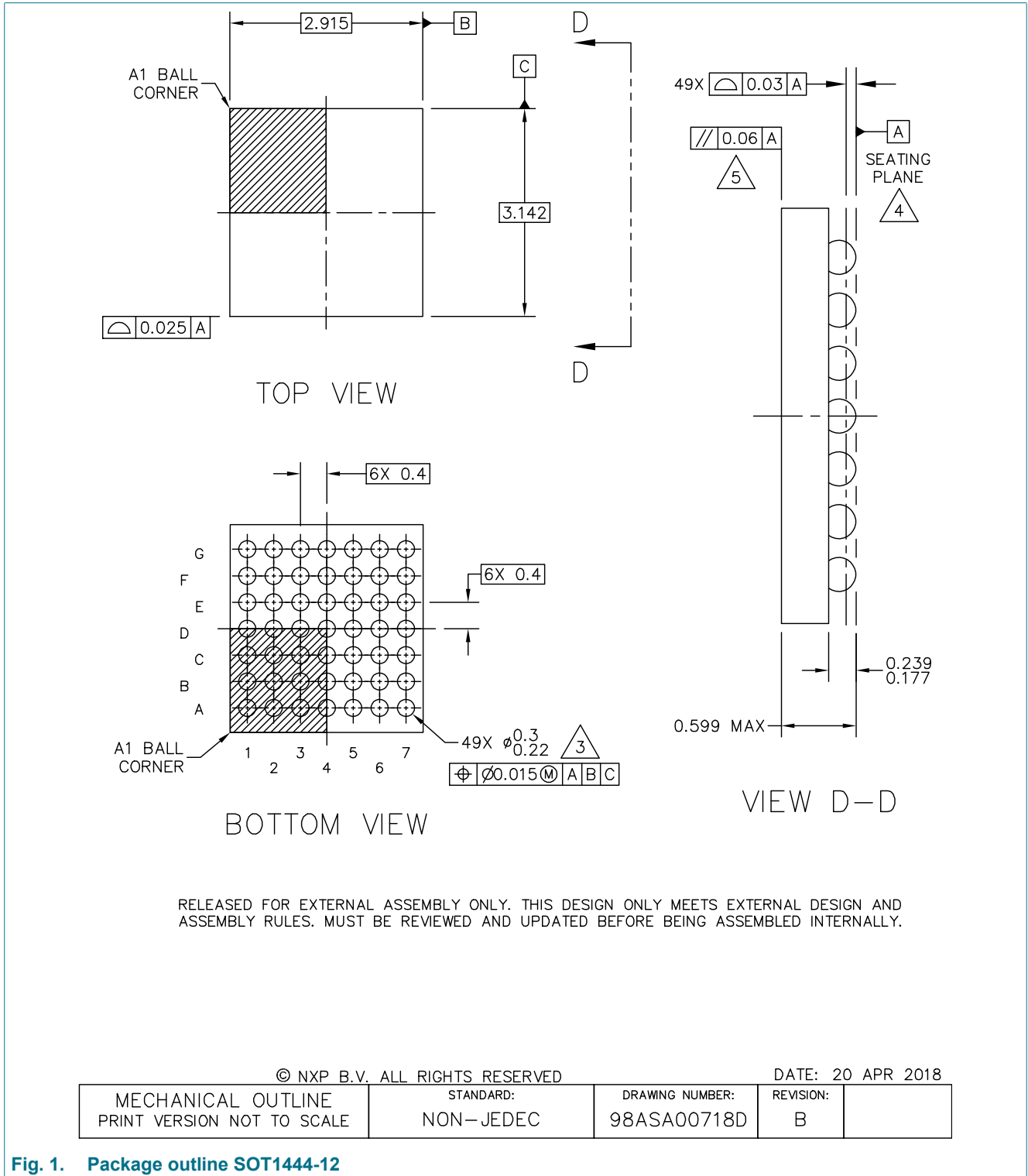


Fig. 1. Package outline SOT1444-12

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5–2009.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 20 APR 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA00718D	REVISION: B	
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Fig. 2. Package outline note WLCSP49 (SOT1444-12)

3. Legal information

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Date of release: 28 May 2018
